

Amendments to the Claims:

Claims 1 and 2 have been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Currently Amended) A semiconductor die having a bond pad arrangement thereon to facilitate packaging thereof, comprising:
a rectangular body having an active surface and a longitudinal centerline; and
a plurality of bond pads disposed adjacent the longitudinal centerline, wherein the plurality of bond pads has a longitudinal length along the longitudinal centerline determined by a longitudinal extent of the plurality of bond pads if equidistantly spaced in a given number of at least one longitudinal row, and wherein the plurality of bond pads are arranged in a same number of longitudinal rows as the given number at least one longitudinal row and
comprising at least two longitudinally adjacent groups of bond pads, each bond pad within a group of bond pads being longitudinally separated from adjacent bond pads within the same group of bond pads by an equal interpad spacing of less than about 0.5 mm
an interpad spacing if all of the bond pads of the plurality were equidistantly spaced,
each group of bond pads being separated from at least one longitudinally adjacent groups
group of bond pads by an intergroup spacing of greater than about 0.5 mmthe equal
interpad spacing,
wherein a longitudinal length of the at least two groups of bond pads and an intergroup spacing
therebetween is substantially the same as the longitudinal length along the longitudinal
centerline determined by a longitudinal extent of the plurality of bond pads if
equidistantly spaced.

2. (Original) The semiconductor die of claim 1, wherein the at least two longitudinally adjacent groups of bond pads consists of two longitudinally adjacent groups.
3. (Original) The semiconductor die of claim 1, wherein the at least one longitudinal row comprises two longitudinal rows flanking the longitudinal centerline.
4. (Previously Presented) The semiconductor die of claim 1, wherein the intergroup spacing is about 1.5 times the interpad spacing.
5. (Previously Presented) The semiconductor die of claim 4, wherein the interpad spacing is about 0.4 mm and the intergroup spacing is about 0.6 mm.